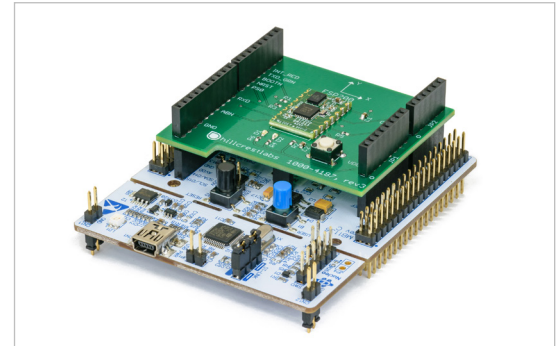


FSP200 Development Suite

The FSP200 is a 6-axis sensor hub with embedded sensor fusion and our new Interactive Calibration that provides exceptional heading accuracy for robots, with your choice of consumer grade MEMS sensors.

Built for rapid development, the FSP200 Development Suite allows you to build applications from evaluations through prototyping and production, incorporating superior motion processing.



FSP200

AVAILABLE PRODUCTS

- ✓ **FSP200 BMI055 Reference Module** - Made for rapid prototyping, the FSP200-BMI055 Reference Module pairs the FSP200 processor with the Bosch Sensortech BMI055 6-axis motion sensor in a self-contained module. This component makes integration and testing with the FSP200 truly turn-key.

- ✓ **FSP200 Serial/USB Adapter** - Designed for instantaneous evaluation, the FSP200 Serial/USB adapter provides the FSP200-BMI055 Reference Module with a USB interface. Simply connect to a PC and receive an always-on stream of the most commonly used sensor data. If deeper interaction and configuration is needed, the included MotionStudio2 PC application supports the full set of FSP200 functionality.

- ✓ **FSP200 Development Kit** - Built for rapid development, the FSP200 Development Kit allows the user to build applications incorporating the FSP200's superior motion processing quickly and efficiently. The FSP200 Development Kit consists of an FSP200 Development Board (including an FSP200-BMI055 Reference Module) and an STMicroelectronics NucleoF411RE Development Platform. The kit also comes with Hillcrest's MotionStudio2 PC application and all documentation, schematics, and software examples necessary to build robust robotics applications.



ABOUT CEVA

CEVA is the leading licensor of wireless connectivity and smart sensing technologies. We offer Digital Signal Processors, AI processors, wireless platforms and complementary software for sensor fusion, image enhancement, computer vision, voice input and artificial intelligence, all of which are key enabling technologies for a smarter, connected world. We partner with semiconductor companies and OEMs worldwide to create power-efficient, intelligent and connected devices for a range of end markets, including mobile, consumer, automotive, robotics, industrial and IoT. Our ultra-low-power IPs include comprehensive DSP-based platforms for 5G baseband processing in mobile and infrastructure, advanced imaging and computer vision for any camera-enabled device and audio/voice/speech and ultra-low power always-on/sensing applications for multiple IoT markets. For sensor fusion, our Hillcrest Labs sensor processing technologies provide a broad range of sensor fusion software and IMU solutions for AR/VR, robotics, remote controls, and IoT. For artificial intelligence, we offer a family of AI processors capable of handling the complete gamut of neural network workloads, on-device. For wireless IoT, we offer the industry's most widely adopted IPs for Bluetooth (low energy and dual mode), Wi-Fi 4/5/6 (802.11n/ac/ax) and NB-IoT.

© Copyright 09/2019 CEVA, Inc. and/or its subsidiaries. All rights reserved. All specifications are subject to change without notice.

